

## **☆TDK** Multilayer Ceramic Chip Capacitors

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Creation Date: October 22, 2014

## C3225X7R2A225K230AB (TDK item description : C3225X7R2A225KT\*\*\*\*)

**Applications** 



Commercial Grade



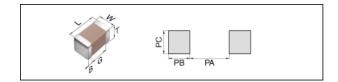
Please refer to Part No. CGA6N3X7R2A225K230AB for automotive use.

Feature

Mid Voltage (100 to 630V)

Series

C3225 [EIA CC1210]











Size	
Length(L)	3.20mm +/-0.40mm
Width(W)	2.50mm +/-0.30mm
Thickness(T)	2.30mm +/-0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern(PA)	2.00 to 2.40mm
Recommended Land Pattern(PB)	1.00 to 1.20mm
Recommended Land Pattern(PC)	1.90 to 2.50mm
Recommended Slit Pattern(SD)	

Electrical Characteristics	
Capacitance	2.2uF +/-10%
Rated Voltage	100Vdc
Temperature Characteristic	X7R(+/-15%)
Dissipation Factor	3% Max.
Insulation Resistance	227MΩ Min.

Other	
Soldering Method	Reflow
AEC Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000Pcs Min.

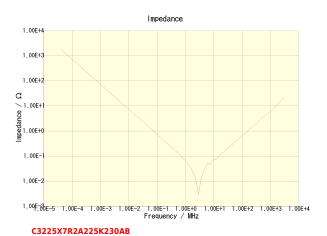
<sup>•</sup>This PDF document was created based on the data listed on the TDK Corporation website.

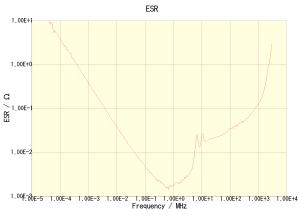
<sup>•</sup>All specifications are subject to change without notice.

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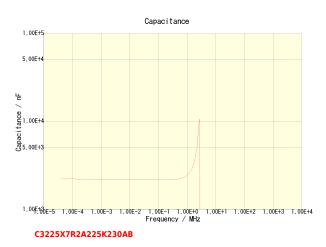
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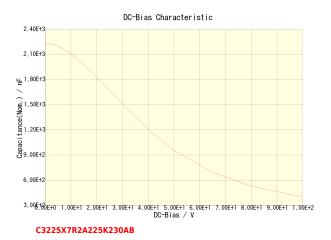
## Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)

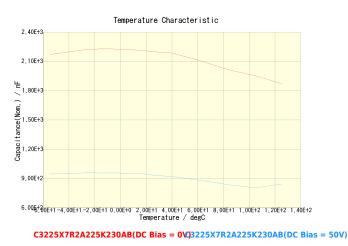




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